

FEATURES

- Low Capacitance
- Up to 6500 μmho Transconductance

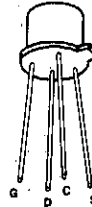
ABSOLUTE MAXIMUM RATINGS

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Gate-Source Voltage	-50V
Gate-Drain Voltage	-50V
Gate Current	10 mA
Storage Temperature Range	-65°C to +200°C
Operating Temperature Range	-55°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C
Power Dissipation	300 mW
Derate above 25°C	1.7 mW/°C

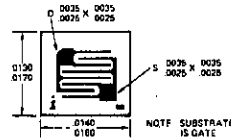
PIN CONFIGURATION

TO-72



CHIP TOPOGRAPHY

5003



ORDERING INFORMATION*

TO-72	WAFER	DICE
2N3821	2N3821/W	2N3821/D
2N3822	2N3822/W	2N3822/D

*When ordering wafer/dice refer to Appendix B-23.

ELECTRICAL CHARACTERISTICS (25°C unless otherwise noted)

PARAMETER		2N3821		2N3822		UNIT	TEST CONDITIONS
		MIN	MAX	MIN	MAX		
I_{GSS}	Gate Reverse Current		-0.1	-0.1	-0.1	nA	$V_{GS} = -30\text{ V}, V_{DS} = 0$
			-0.1	-0.1	-0.1	μA	
BV_{GSS}	Gate-Source Breakdown Voltage	-50		-50		V	$I_G = -1\ \mu\text{A}, V_{DS} = 0$ $V_{DS} = 15\text{ V}, I_D = 0.5\ \text{nA}$ $V_{DS} = 15\text{ V}, I_D = 50\ \mu\text{A}$ $V_{DS} = 15\text{ V}, I_D = 200\ \mu\text{A}$
$V_{GS(off)}$	Gate-Source Cutoff Voltage		-4		-6		
V_{GS}	Gate-Source Voltage	-0.5	-2		-4		
I_{DSS}	Saturation Drain Current	0.5	2.5	2	10	mA	$V_{DS} = 15\text{ V}, V_{GS} = 0$
g_{fs}	Common-Source Forward Transconductance (Note 1)	1500	4500	3000	6500	μmho	$f = 1\ \text{kHz}$
$ y_{fs} $	Common-Source Forward Transadmittance	1500		3000			$f = 100\ \text{MHz}$
g_{os}	Common-Source Output Conductance (Note 1)		10		20		$f = 1\ \text{kHz}$
C_{iss}	Common-Source Input Capacitance		6		6	pF	$V_{DS} = 15\text{ V}, V_{GS} = 0$
C_{rss}	Common-Source Reverse Transfer Capacitance		3		3		
NF	Noise Figure		5		5	dB	$V_{DS} = 15\text{ V}, V_{GS} = 0,$ $R_{gen} = 1\ \text{meg}, BW = 5\ \text{Hz}$
\bar{e}_n	Equivalent Input Noise Voltage		200		200	$\frac{\text{nV}}{\sqrt{\text{Hz}}}$	$V_{DS} = 15\text{ V}, V_{GS} = 0, BW = 5\ \text{Hz}$ $f = 10\ \text{Hz}$

Note 1: These parameters are measured during a 2 msec interval 100 msec after DC power is applied.